

# 10T eSIM (eUICC)

TECHNICAL SHEET (INDUSTRIAL)

## MFF2/EMBEDDED

### Hardware features

- Industrial grade qualification (JEDEC)
- Operating temperature: -40 to 105 °C
- Data Retention: 17 years at 85°C; 10 years at 105°C
- Erase/Write Cycles : 500.000 cycles
- Up to 1280 Kbytes of User Flash Memory
- Up to 32 Kbytes of User RAM
- 1.8 V, 3 V and 5 V supply voltage ranges
- Current consumption compatible with GSM and ETSI specifications
- Power-saving standby state
- ESD protection greater than 4 kV (HBM)

### Security features

- Active shield
- Memory protection unit (MPU)
- Monitoring of environmental parameters
- Protection against faults
- 16- and 32-bit CRC calculation block (ISO 13239, IEEE 802.3, etc.)
- True random number generator



Fully compliant with GSMA's RSP specifications - SGP.01, SGP.02, SGP.11.



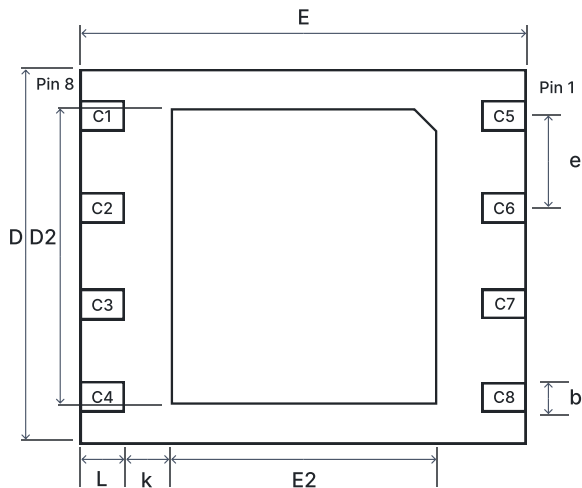
- Hardware security-enhanced DES accelerator
- Hardware security-enhanced AES accelerator
- NESCRYPT coprocessor for public key cryptography algorithm

### Software features

- 2G/3G/4G/5G (U)SIM ETSI/3GPP Features
- ISIM ETSI/3GPP Features
- LPWA (U)SIM ETSI/3GPP Features
- JavaCard and GlobalPlatform Features
- OTA SMS, BIP/HTTPS, BIP/CAT-TP Features
- Dynamic Memory Management
- EAP Methods



### MFF2 bottom view



Package pin to UICC contact mapping

Package pin	UICC contact	Package pin	UICC contact
1	C5	8	C1
2	C6	7	C2
3	C7	6	C3
4	C8	5	C4

Dimensions of the MFF2

Parameter	Description	Dimensions (mm)
E	The package body dimension in the horizontal direction.	6,00 ± 0,15
D	The package body dimension in the vertical direction.	5,00 ± 0,15
L	The length of the contact as measured from the edge of the package.	0,60 ± 0,15
b	The width of the metallised contacts (including lead finish) exposed at the bottom surface of the package.	0,40 ± 0,10
E2	The horizontal dimension of the exposed metal heat feature (exposed die pad).	min 3,30
D2	The vertical dimension of the exposed metal heat feature (exposed die pad).	min 3,90
k	The gap between any contact and the heat feature.	min 0,20
e	The centreline-to-centreline spacing of the contacts.	1,27 for tolerances see parameters bbb and ddd
bbb	The tolerance that controls the position of the contact pattern with respect to the horizontal package centreline. The centre of the tolerance zone for each contact is defined by basic dimension e as related to the horizontal package centreline.	0,10
ddd	The tolerance that controls the position of the contacts to each other. The centres of the profile zones are defined by basic dimension e.	0,05